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Solder foil used for forming a semiconductor device is made by rolling metal particles such as copper particles and a material containing tin particles

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Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
WO 200249797	A1	20020627	WO 2001JP11152	A	20011219	200254	B
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Patent Details

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Abstract:

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NOVELTY Solder foil formed by rolling metal particles such as copper particles and a material containing tin particles as solder particles is suitable for high-temperature-side solder-joining in a temperature-step solder-joining.

USE The solder foil is used for forming a semiconductor device and an electronic device.

ADVANTAGE A semiconductor device and an electronic device obtained by using such solder joining are excellent in mechanical characteristics and reliability.

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